BOARD CHARACTERISTICS

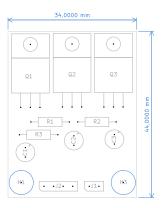
Copper Layer Count: Board Thickness: 1,6000 mm

Board overall dimensions: 34,0000 mm x 43,5000 mm

Min track/spacing: 0,0000 mm / 0,0000 mm Min hole diameter: 0,3000 mm

Copper Finish: Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors:



Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Direct Printing	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0,01 mm	Green	3,3	0
F.Cu	copper		0,035 mm		1	0
Dielectric 1	core	FR4	1,51 mm	FR4 natural	4,5	0,02
B.Cu	copper		0,035 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0,01 mm	Green	3,3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Direct Printing	0 mm	White	1	0



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Maykol Rey

Sheet: Date: 2023-02-22 Size: A4 Title: RGB HOVER

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